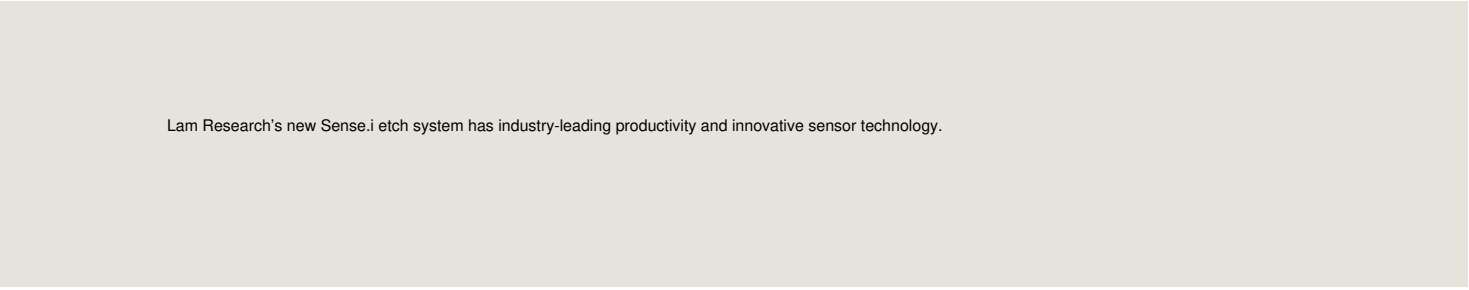
Lam Research Breaks New Ground in Etch Technology and Productivity for Chipmaking Processes

Lam's new Sense.i platform delivers industry-leading output and innovative sensor technology

FREMONT, Calif., March 03, 2020 (GLOBE NEWSWIRE) -- Lam Research Corp. (Nasdaq: LRCX) today announced the launch of a completely transformed plasma etch technology and system solution, designed to provide chipmakers with advanced functionality and extendibility required for future innovation. Lam's groundbreaking Sense.i™ platform offers unparalleled system intelligence in a compact, high-density architecture to deliver process performance at the highest productivity, supporting logic and memory device roadmaps through the coming decade.



Lam Research's new Sense.i etch system has industry-leading productivity and innovative sensor technology.

With core technology evolved from Lam's industry-leading Kiyo® and Flex® process modules, the Sense.i platform enables the critical etch capabilities required to continue advancing uniformity and etch profile control for maximizing yield and lowering wafer costs. As dimensions shrink and aspect ratios increase, the Sense.i platform is designed to support future technology inflections.

Powered by Lam's Equipment Intelligence® technology, the self-aware Sense.i platform enables semiconductor manufacturers to capture and analyze data, identify patterns and trends, and specify actions for improvement. Sense.i also features autonomous calibration and maintenance capabilities that reduce downtime and labor costs, and delivers machine learning algorithms that allow the tool to self-adapt to minimize process variations and maximize wafer output.

The Sense.i platform has a revolutionary space-saving architecture that will help customers meet their future wafer output targets by producing more than a 50% improvement in etch output density. As semiconductor manufacturers develop smarter, faster, and denser chips, processes are rapidly growing in complexity and number of steps. This requires a greater number of process chambers in a fab and reduces total output for a given floor space. The Sense.i platform's smaller footprint benefits either a new fab build or a fab undergoing a node-to-node technology conversion.

"Lam is introducing the most innovative etch product that has been developed in the last 20 years," said Vahid Vahedi, senior vice president and general manager of the Etch product group at Lam Research. "Sense.i extends our technology roadmap to meet our customers' next-generation requirements while solving the critical cost scaling challenges they're facing in their business. With more than four million wafers processed on Lam etch systems every month, Lam has an installed-base that provides extraordinary learning to innovate, design, and produce the best tools for semiconductor manufacturing."

For more information about Sense.i visit the product page. Watch this video for an overview of the new etch system.

About Lam Research
Lam Research Corporation is a global supplier of innovative wafer fabrication equipment and services to the semiconductor industry. As a trusted, collaborative partner to the world's leading semiconductor companies, we combine superior systems engineering capability, technology leadership, and unwavering commitment to customer success to accelerate innovation through enhanced device performance. In fact, today, nearly every advanced chip is built with Lam technology. Lam Research (Nasdaq: LRCX) is a FORTUNE 500® company headquartered in Fremont, Calif., with operations around the globe. Learn more at www.lamresearch.com. (LRCX-P)

Caution Regarding Forward-Looking Statements
Statements made in this press release that are not of historical fact are forward-looking statements and are subject to the safe harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements relate to, but are not limited: the performance of the tools we sell or service; the requirements of our customers for future innovation and the ability of our tools to meet the customers' future requirements; future process requirements in the semiconductor industry; the cost effectiveness of our tool offerings; the learning that we may obtain from our installed base and our ability to increase etch output density and wafer output per area, and hence increase efficiency and output for customers. These statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, significance, value and effect including those risks and uncertainties that are described in the documents filed or furnished by us with the Securities and Exchange Commission, including specifically our annual report on Form 10-K for the fiscal year ended June 30, 2019 and our quarterly reports on Form 10-Q for the fiscal quarters ended December 29, 2019 and September 29, 2019. These uncertainties and changes could materially affect the forward-looking statements and cause actual results to vary from expectations in a material way. The Company undertakes no obligation to update the information or statements made in this release.

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A photo accompanying this announcement is available at https://www.globenewswire.com/NewsRoom/AttachmentNg/6e39eb23-7c15-4100-a31f-795546f25c90

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